

**SLOVENSKI
STANDARD**

SIST EN 60286-3:2002

prva izdaja
september 2002

Packaging of components for automatic handling - Part 3: Packaging of surface mount components on continuous tapes (IEC 60286-3:1997)

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ICS 31.020; 55.060

Referenčna številka
SIST EN 60286-3:2002(en)

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Descriptors: Electronic components, packaging, continuous tapes

English version

Packaging of components for automatic handling
Part 3: Packaging of surface mount components on continuous tapes
(IEC 60286-3:1997)

Emballage de composants pour
opérations automatisées
Partie 3: Emballage des composants
appropriés au montage en surface en
bandes continues
(CEI 60286-3:1997)

Gurtung und Magazinierung von
Bauelementen für automatische
Verarbeitung
Teil 3: Gurtung von
oberflächenmontierbaren Bauelementen
(IEC 60286-3:1997)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 40/942/FDIS, future edition 3 of IEC 60286-3, prepared by IEC TC 40, Capacitors and resistors for electronic equipment, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60286-3 on 1998-01-01.

This European Standard supersedes HD 143.3 S2:1992.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 1998-10-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 1998-10-01

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60286-3:1997 was approved by CENELEC as a European Standard without any modification.

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Annex ZA (normative)

**Normative references to international publications
with their corresponding European publications**

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE: When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-2	1966	Mechanical standardization of semiconductor devices Part 2: Dimensions	-	-
ISO 11469	1993	Plastics - Generic identification and marking of plastic products	-	-

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**NORME
INTERNATIONALE
INTERNATIONAL
STANDARD**

**CEI
IEC**

60286-3

Troisième édition
Third edition
1997-12

**Emballage de composants pour
opérations automatisées –**

**Partie 3:
Emballage des composants appropriés
au montage en surface en bandes continues**

**Packaging of components for
automatic handling –**

**Part 3:
Packaging of surface mount components
on continuous tapes**

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Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

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Pour prix, voir catalogue en vigueur
For price, see current catalogue

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 3: Packaging of surface mount components
on continuous tapes

FOREWORD

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of the IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested National Committees.
- 3) The documents produced have the form of recommendations for international use and are published in the form of standards, technical reports or guides and they are accepted by the National Committees in that sense.
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International Standard IEC 60286-3 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment.

This third edition cancels and replaces the second edition published in 1991 and constitutes a technical revision.

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The text of this standard is based on the following documents:

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FDIS	Report on voting
https://standards.iteh.ai/standards/sist/40/942/FDIS/standards/sist/40/1035/RVD48a4-affed34a900a0dc1/sist-cn-60286-3-2002	

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

INTRODUCTION

Tape packaging meets the requirements of automatic component placement machines and also covers the use of tape packaging for components for test purposes and other operations.

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PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –

Part 3: Packaging of surface mount components on continuous tapes

1 General

1.1 Scope

This Standard is applicable to the tape packaging of electronic components without leads or with lead stumps which are intended to be connected to electronic circuits. It includes only those dimensions which are essential for the taping of components intended for the above-mentioned purposes.

1.2 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 60286. At the time of publication, the editions indicated were valid. All normative documents are subject to revision, and parties to agreements based on this part of IEC 60286 are encouraged to investigate the possibility of applying the most recent editions of the normative documents indicated below. Members of IEC and ISO maintain registers of currently valid International Standards

IEC 60191-2: 1966, *Mechanical standardization of semiconductor devices – Part 2: Dimensions*

ISO 11469: 1993, *Plastics – Generic identification and marking of plastic products*

2 Dimensions

2.1 TYPE I (Punched tape)

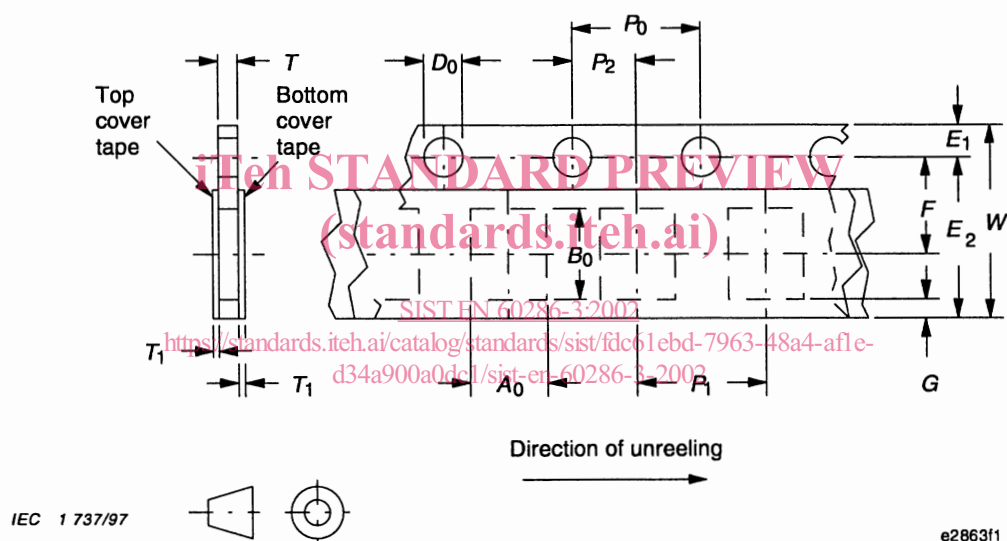


Figure 1 – Punched carrier tape